

	Ref #	Search Text
34	S34	stack\$3 near4 (die chip)
35	S37	(seal\$3 underfill\$3) near5 (die chip)
36	S36	(connector\$3 (solder near2 ball)) near5 (die chip)
37	S40	("4706166" "4807021" "4897708" "4954875" "4984358" "4996583" "5049979" "5104820" "5138438" "5332922" "5394303" "5484959" "5514907" "5625221" "5744827" "5804874" "5854507" "5861666" "5877478" "5910685" "5973393" "6072233" "6084294" "6124633").PN.
38	S39	("5634268" "5796591" "5821624" "6337513" "6509639" "6644536").PN.
39	S38	S35 same S36 same S37
40	S35	(dual multi multiple) near3 stack\$3 near4 (die chip)
41	S44	S41 and S42 and S43
42	S53	("6873036").URPN.
43	S51	("20010015485" "4996587" "5444296" "5652463" "5674785" "5808878" "5898224" "5952611" "5973403" "5994166" "5994773" "6005778" "6013948" "6020629" "6051878" "6081023" "6087717" "6181002" "6262488" "6265771" "6316727").PN.
44	S50	(S41 and S47) and S43
45	S56	("6337513").URPN.

	DBs
34	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB
35	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB
36	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB
37	US-PGPUB; USPAT; USOCR
38	US-PGPUB; USPAT; USOCR
39	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB
40	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB
41	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB
42	USPAT
43	US-PGPUB; USPAT; USOCR
44	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB
45	USPAT

	Ref #	Search Text
46	S57	("4706166" "4807021" "4897708" "4954875" "4984358" "4996583" "5049979" "5104820" "5138438" "5332922" "5394303" "5484959" "5514907" "5625221" "5744827" "5804874" "5854507" "5861666" "5877478" "5910685" "5973393" "6072233" "6084294" "6124633").PN.
47	S55	("4597714" "4979015" "4996116" "5308980" "5334342" "5364923" "5387555" "5423475" "5573979" "5647998" "5650639" "5679264" "5683939" "5744383" "5744865" "5747918" "5750243" "5796714" "5855998" "5874775" "5897924" "5899728" "5902686" "5909280" "5977697" "6124198").PN.
48	S60	("6820329").URPN.
49	S59	("6509639").URPN.
50	S58	("6509639").URPN.
51	S61	("20010015485" "4996587" "5444296" "5652463" "5674785" "5808878" "5898224" "5952611" "5973403" "5994166" "5994773" "6005778" "6013948" "6020629" "6051878" "6081023" "6087717" "6181002" "6262488" "6265771" "6316727").PN.
52	S66	(257/777).CCLS.
53	S67	(257/778).CCLS.
54	S63	(connector\$3 (solder near2 ball)) near4 adhesive
55	S65	S63 same S41
56	S46	("6820329").URPN.
57	S47	(connector\$3 (solder near2 ball)) near5 (die chip) near5 (substrate wafer)
58	S54	("5634268" "5796591" "5821624" "6337513" "6509639" "6644536").PN.

	DBs
46	US-PGPUB; USPAT; USOCR
47	US-PGPUB; USPAT; USOCR
48	USPAT
49	USPAT
50	USPAT
51	US-PGPUB; USPAT; USOCR
52	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB
53	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB
54	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB
55	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB
56	USPAT
57	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB
58	US-PGPUB; USPAT; USOCR

	Ref #	Search Text
59	S42	(connector\$3 (solder near2 ball)) near5 (die chip)
60	S43	(seal\$3 underfill\$3) near5 (die chip)
61	S49	(S41 same S47)
62	S45	("5634268" "5796591" "5821624" "6337513" "6509639" "6644536").PN.
63	S52	("2006/0097402").URPN.
64	S69	S68 and S66
65	S68	(seal\$3 underfill\$3) with (die chip)
66	S64	S63 and S41
67	S62	("6441483").URPN.
68	S41	(dual multi multiple) near3 stack\$3 near4 (die chip)
69	S48	(S41 same S47) and S43
70	S70	((("6566745") or ("6777268") or ("6613606"))).PN.

	DBs
59	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB
60	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB
61	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB
62	US-PGPUB; USPAT; USOCR
63	USPAT
64	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB
65	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB
66	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB
67	USPAT
68	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB
69	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB
70	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB

	L #	Search Text
1	L10	(438/108).CCLS.
2	L11	(438/109).CCLS.
3	L12	(438/118).CCLS.
4	L13	(257/E21.705).CCLS.
5	L14	(257/e21.503).CCLS.
6	L15	(257/686).CCLS.
7	L16	(257/777).CCLS.
8	L17	(257/737).CCLS.
9	L18	(257/681).CCLS.
10	L19	(257/778).CCLS.
11	L20	(257/e25.013).CCLS.

	DBs
1	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB
2	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB
3	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB
4	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB
5	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB
6	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB
7	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB
8	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB
9	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB
10	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB
11	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB